# SIEMENS

**Data sheet**          **6DL1193-6BP00-0BX1**

SIMATIC ET 200SP HA, ET 200SP, BaseUnit type X1, for Ex electronic modules, push-in terminals, WxH: 20 mm x 117 mm

| General information | |
|---|---|
| Product type designation | BU type X1 |
| Product function | |
| ● I&M data | Yes; Asset data |
| **Current carrying capacity** | |
| For P1 and P2 bus, max. | 10 A |
| For process terminals, max. | 0.5 A |
| **Hardware configuration** | |
| Temperature sensor | Yes; For internal reference junction with connecting thermocouple |
| Formation of potential groups | |
| ● support of potential groups | Yes |
| ● New potential group | No |
| ● Potential group continued from the left | Yes |
| Slots | |
| ● Number of slots | 1 |
| **Potential separation** | |
| between backplane bus and supply voltage | Yes |
| between process terminals and supply voltage | Yes |
| **Isolation** | |
| Isolation tested with | further information on insulation can be found in the "ET 200SP HA / ET 200SP modules for devices in hazardous areas" System Manual |
| **Ambient conditions** | |
| Ambient temperature during operation | |
| ● horizontal installation, min. | -40 °C |
| ● horizontal installation, max. | 70 °C |
| ● vertical installation, min. | -40 °C |
| ● vertical installation, max. | 60 °C |
| Altitude during operation relating to sea level | |
| ● Installation altitude above sea level, max. | 2 000 m |
| **connection method / header** | |
| Terminals | |
| ● Terminal type | Push-in terminal |
| ● Conductor cross-section, min. | 0.14 mm²; AWG 26 |
| ● Conductor cross-section, max. | 2.5 mm²; AWG 14 |
| ● Number of process terminals to I/O module | 8 |
| **Dimensions** | |
| Width | 20 mm |
| Height | 117 mm |
| Depth | 35 mm |
| **Weights** | |

| Weight, approx. | 42 g |
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| **last modified:** | 5/7/2021 [↗] |

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